



# Silicon Wafer Japan TC Chapter

Japan Standards Winter 2022 Meetings

Wednesday, May 25, 2022

<10:00 –12:00 JST> via Virtual Meeting

## AGENDA

	<b>Time</b>
<b>1 Welcome/Call to Order</b>	<b>10:00</b>
1.1 Introductions	
1.2 Required Elements (Membership Requirements, Antitrust and Intellectual Property Reminders, and Effective Meeting Guidelines)	
1.3 Agenda Review	
<b>2 Review of Previous Meeting Minutes</b>	
<b>3 Ballot Review</b>	
3.1 Cycle 3-2022 submitted by the Japan TC Chapter	
3.1.1 Doc.6570 - New Standard: Guide for Measuring Bulk Micro Defect Density and Denuded Zone Width in Annealed Silicon Wafers by a Laser-Scatter Tomography Technique	
<b>4 Subcommittee &amp; Task Force Reports</b>	
4.1 International Advanced Wafer Geometry TF	
4.2 International / Japan Test Method TF	
4.3 International Advanced Surface Inspection TF	
4.4 International Polished Wafers TF	
4.5 International Epitaxial Wafers TF	
4.6 International Annealed Wafers TF	
4.7 International SOI Wafers TF	
4.8 International Terminology TF	
4.9 JA Shipping Box TF	
<b>5 Liaison Report</b>	
5.1 Europe TC Chapter	
5.2 North America TC Chapter	
5.3 GCS Report	
<b>6 Staff Report</b>	

**7 Old Business**

7.1 Project Period Review

7.1.1 #6687 SNARF for: Revision of M51: Test Method for Characterizing Silicon Wafer by Gate Oxide Integrity

7.2 5 Year Review Check

7.2.1 SEMI M51-1012: Test Method for Characterizing Silicon Wafer by Gate Oxide Integrity

7.2.2 SEMI M60-1014: Test Method for Time Dependent Dielectric Breakdown Characteristics of SiO<sub>2</sub> Films for Si Wafer Evaluation

**8 New Business**

None

**9 Action Item Review**

9.1 Open Action Items

9.2 New Action Items

**10 Next Meeting and Adjournment**

**12:00**

10.1 The next meeting is scheduled for <date> at <event/location>.